

## CLAIMS

We claim:

- 1           1. A method for attaching a module to a printed circuit board comprising  
2 the steps of:  
3           attaching a standoff to the module;  
4           applying a ball grid array to the module;  
5           positioning the module such that the standoff is between the printed  
6 circuit board and the module; and  
7           reflowing the ball grid array.

- 1           2. An electrical attachment comprising:  
2           a module having connection pads on a bottom surface;  
3           a standoff, positioned on the bottom surface, having a height;  
4           a printed circuit board having connection pads;  
5           a ball grid array, interposing the connection pads of the module and the  
6 printed circuit board, wherein the height of the ball grid array is comparable to  
7 the height of the standoff. (US, 2001, 01, 25)

- 1           3. An electrical attachment, as defined in claim 2, wherein the standoff is  
2 an insulative material.

- 1           4. An electrical attachment, as defined in claim 3, wherein the insulative  
2 material is silicon.

- 1           5. An electrical attachment, as defined in claim 2, further comprising a  
2 flexible circuit interposing the module and the standoff.

- 1           6. An electrical attachment, as defined in claim 5, wherein the standoff is  
2 an insulative material.

- 1           7. An electrical attachment, as defined in claim 6, wherein the insulative  
2 material is silicon.